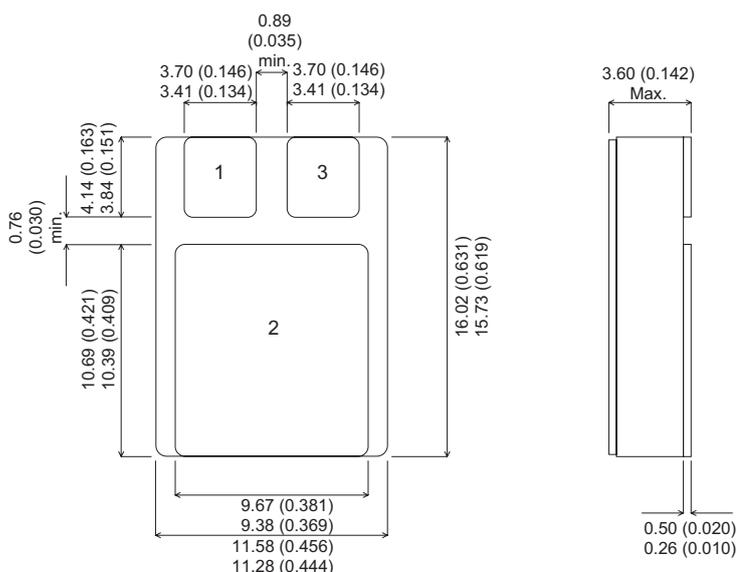


MECHANICAL DATA

Dimensions in mm (inches)


**N-CHANNEL
POWER MOSFET**

V_{DSS} **100V**
 $I_{D(cont)}$ **45A**
 $R_{DS(on)}$ **0.028Ω**

FEATURES

- HERMETICALLY SEALED SURFACE MOUNT PACKAGE
- SMALL FOOTPRINT – EFFICIENT USE OF PCB SPACE.
- SIMPLE DRIVE REQUIREMENTS
- LIGHTWEIGHT
- HIGH PACKING DENSITIES

SMD 1 PACKAGE (TO-276AB)

Pad 1 – Source Pad 2 – Drain Pad 3 – Gate

Note: IRF3710SMD also available with pins 1 and 3 reversed.

ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^{\circ}C$ unless otherwise stated)

V_{GS}	Gate – Source Voltage	±20V
I_D	Continuous Drain Current ($V_{GS} = 0$, $T_{case} = 25^{\circ}C$)	45A
I_D	Continuous Drain Current ($V_{GS} = 0$, $T_{case} = 100^{\circ}C$)	30A
I_{DM}	Pulsed Drain Current ¹	180A
P_D	Power Dissipation @ $T_{case} = 25^{\circ}C$	125W
	Linear Derating Factor	1.0W/°C
E_{AS}	Single Pulse Avalanche Energy ²	250mJ
dv/dt	Peak Diode Recovery ³	3.7V/ns
T_J , T_{stg}	Operating and Storage Temperature Range	-55 to 150°C
T_L	Package Mounting Surface Temperature (for 5 sec)	300°C
$R_{\theta JC}$	Thermal Resistance Junction to Case	1.0°C/W

Notes 1) Pulse Test: Pulse Width $\leq 300ms$, $\delta \leq 2\%$

 2) @ $V_{DD} = 25V$, $L \geq 0.64mH$, Peak $I_{AS} = 28A$, $V_{GS} = 10V$, $R_G = 25\Omega$, Starting $T_J = 25^{\circ}C$

 3) @ $I_{SD} \leq 28A$, $di/dt \leq 390A/\mu s$, $V_{DD} \leq 100V$, $T_J \leq 150^{\circ}C$

Semelab Plc reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by Semelab is believed to be both accurate and reliable at the time of going to press. However Semelab assumes no responsibility for any errors or omissions discovered in its use. Semelab encourages customers to verify that datasheets are current before placing orders.

ELECTRICAL CHARACTERISTICS ($T_{amb} = 25^{\circ}\text{C}$ unless otherwise stated)

Parameter	Test Conditions	Min.	Typ.	Max.	Unit	
STATIC ELECTRICAL RATINGS						
BV_{DSS}	Drain – Source Breakdown Voltage	$V_{GS} = 0$	$I_D = 250\mu\text{A}$	100	V	
ΔBV_{DSS}	Temperature Coefficient of Breakdown Voltage	Reference to 25°C		0.104	$\text{V}/^{\circ}\text{C}$	
$R_{DS(on)}$	Static Drain – Source On–State Resistance ¹	$V_{GS} = 10\text{V}$	$I_D = 28\text{A}$	0.028	Ω	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$	$I_D = 250\mu\text{A}$	2.0	V	
g_{fs}	Forward Transconductance ¹	$V_{DS} = 15\text{V}$	$I_{DS} = 28\text{A}$	20	$\text{S}(\bar{\nu})$	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0$	$V_{DS} = 80\text{V}$ $T_J = 125^{\circ}\text{C}$	25 250	μA	
I_{GSS}	Forward Gate – Source Leakage	$V_{GS} = 20\text{V}$		100	nA	
I_{GSS}	Reverse Gate – Source Leakage	$V_{GS} = -20\text{V}$		-100	nA	
DYNAMIC CHARACTERISTICS						
C_{iss}	Input Capacitance	$V_{GS} = 0$		2920	pF	
C_{oss}	Output Capacitance	$V_{DS} = 25\text{V}$		700		
C_{rss}	Reverse Transfer Capacitance	$f = 1\text{MHz}$		340		
Q_g	Total Gate Charge ¹	$V_{GS} = 10\text{V}$	$I_D = 28\text{A}$		200	nC
Q_{gs}	Gate – Source Charge ¹	$I_D = 28\text{A}$			28	nC
Q_{gd}	Gate – Drain (“Miller”) Charge ¹	$V_{GS} = 10\text{V}$	$V_{DS} = 80\text{V}$		94	
$t_{d(on)}$	Turn–On Delay Time	$V_{DD} = 50\text{V}$	$V_{GS} = 10\text{V}$		25	ns
t_r	Rise Time	$I_D = 28\text{A}$			86	
$t_{d(off)}$	Turn–Off Delay Time	$R_G = 2.5\Omega$			75	
t_f	Fall Time				54	
SOURCE – DRAIN DIODE CHARACTERISTICS						
I_S	Continuous Source Current			45	A	
I_{SM}	Pulse Source Current ²			180		
V_{SD}	Diode Forward Voltage	$I_S = 28\text{A}$	$T_J = 25^{\circ}\text{C}$	1.3	V	
t_{rr}	Reverse Recovery Time	$I_F = 28\text{A}$	$T_J = 25^{\circ}\text{C}$	280	ns	
Q_{rr}	Reverse Recovery Charge	$d_i / d_t \leq 100\text{A}/\mu\text{s}$	$V_{DD} \leq 50\text{V}$	2.0	μC	
t_{on}	Forward Turn–On Time			Negligible		

Notes

- 1) Pulse Test: Pulse Width $\leq 300\mu\text{s}$, $\delta \leq 2\%$
- 2) Repetitive Rating – Pulse width limited by maximum junction temperature.

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